CPI0805E3R3R-10

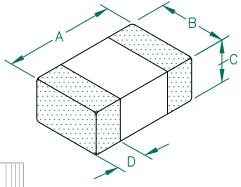
PHYSICAL DIMENSIONS:

Inductance(uH)

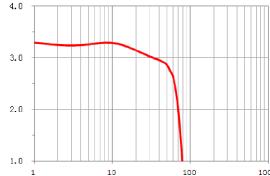
A 2.00 [.079] ± 0.20[.008] ± 0.20[.008] B 1.25 [.049]

± 0.10[.004] C 0.90 [.035]

± 0.20[.008] D 0.50 [.020]

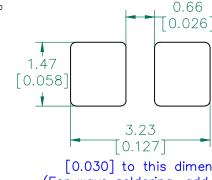


Ls vs Frequency



Frequency (MHz) Ls vs DC BIAS Current

LAND PATTERNS FOR REFLOW SOLDERING



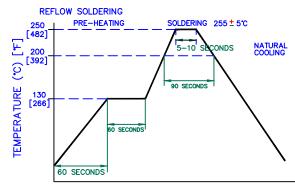
[0.030] to this dimension) (For wave soldering, add 0.763

ELECTRICAL CHARACTERISTICS:									
	L (μΗ) @ 1MHz ± 20%	DCR (Ω)	l (Max)						
Nom	3.3								
Min	2.6								
Max	4.0	0.275	500mA						

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATING TEMPERATURE TEMP: -55° C~+125° C (INCLUDING SELF-HEATING)
- 6. COSMETIC SPECIFICATION REFER TO WI-QA-124

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Lai						
				Tech, and is loaned in confidence			_	.		
				subject to return upon request with the understanding that no	anc	"I airn				
			-	copies shall be made without th	е	Laird				
			_	written consent of Laird Tech. A						
				rights to design or invention are	•	_				
				reserved.						
				PROJECT/PART NUMBER:	- 1	REV	PART T	PE:	DRAWN BY:	
С	CHANGE PLASTIC TAPE TO PAPER TAPE	04/17/14	QU	CPI0805E3R3R-10	-	С	CO-	-FIRE	QU	
В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11	SCA	LE: N	TS	SHEET:		
Α	ORIGINAL DRAFT	03/01/11	QU	, ,	TOO		13			
REV	DESCRIPTION	DATE	INT	CPI0805E3R3R-10-A			_		of 1	

